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PATENT

IN THE UNITED STATES PATENT AND TRADEMARK OFFICE

Application No.: 10/772,311 Group Art Unit: 1732
Filing Date: February 6, 2004 Examiner: Lee, Edmund H.
Applicant: Sang-Hyeop LEE et al.
Title: MOLDING METHOD AND MOLD FOR ENCAPSULATING
BOTH SIDES OF PCB MODULE WITH WAFER LEVEL
PACKAGE MOUNTED PCB
Attorney Docket: 2557-000220/US

Customer Service Window
Randolph Building
401 Dulany Street
Alexandria, VA 22314
Mail Stop Amendment

January 6, 2009

AMENDMENT UNDER 37 C.F.R. §1.111

Sir:

In response to the non-Final Office Action mailed October 8, 2008, the following amendments and remarks are respectfully submitted in connection with the above-identified application.

Amendments to the Claims begin on page 2 of this Amendment.

Remarks begin on page 7 of this Amendment.

	Claims remaining after Amendment		Highest number previously paid for		Present extra
Total	9	-	20	=	0
Independent	2	-	3	=	0